TOSHIBA Power Transistor Module Silicon NPN Epitaxial Type (Four Darlington Power Transistors in One)

# **MP4101**

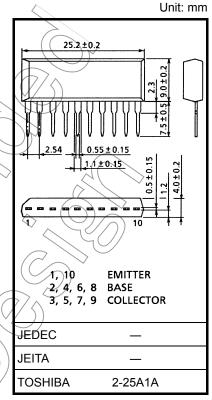
High Power Switching Applications Hammer Drive, Pulse Motor Drive Inductive Load Switching

- Small package by full molding (SIP 10 pins)
- High collector power dissipation (4-device operation) :  $P_T = 4 \text{ W (Ta} = 25^{\circ}\text{C)}$
- High collector current: IC (DC) = 4 A (max)
- High DC current gain:  $h_{FE} = 2000$  (min) ( $V_{CE} = 2$  V,  $I_{C} = 1$  A)
- Zener diode included between collector and base.

#### Absolute Maximum Ratings (Ta = 25°C)

| Characteristics             |       | Symbol  | Rating     | Unit                                      |  |
|-----------------------------|-------|---|------------|---|--|
| Collector-base voltage      |       | $V_{CBO}$                                       | 60 ± 10    | V   |  |
| Collector-emitter voltage   |       | V <sub>CEO</sub>                                | 60 ± 10    | V   |  |
| Emitter-base voltage        |       | V <sub>EBO</sub> <                              | 6          | y   |  |
| Collector current           | DC    | lc (  | 4          | <   |  |
|                             | Pulse | ICP (   | 6          | *   |  |
| Continuous base current     |       | B)  | 0.5        | Α   |  |
| Collector power dissipation |       | $\left(\left\langle R_{C}\right\rangle \right)$ | 2.0        | M   |  |
| (1-device operation)        |       |   | 2.0        |   |  |
| Collector power dissipati   | on (( |   | 10         | $\langle \langle \langle \rangle \rangle$ |  |
| (4-device operation)        |       | <b>₽</b> T ∧                                    | (1)        | ~ VV                                      |  |
| Junction temperature <      |       | ⊃ т <sub>ј</sub>                                | 150        | °C  |  |
| Storage temperature ran     | ge    | T <sub>stg</sub>                                | -55 to 150 | °C  |  |

**Industrial Applications** 

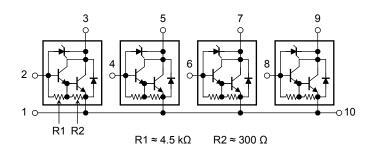


Weight: 2.1 g (typ.)

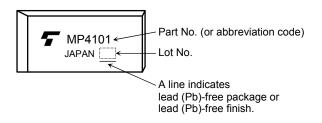
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

### **Array Configuration**



#### Marking

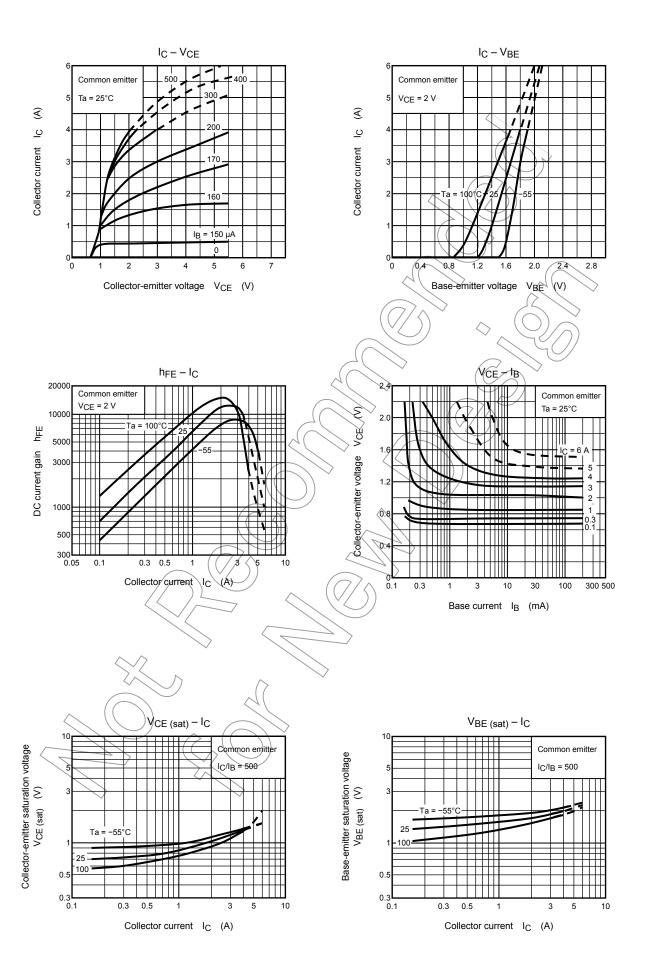


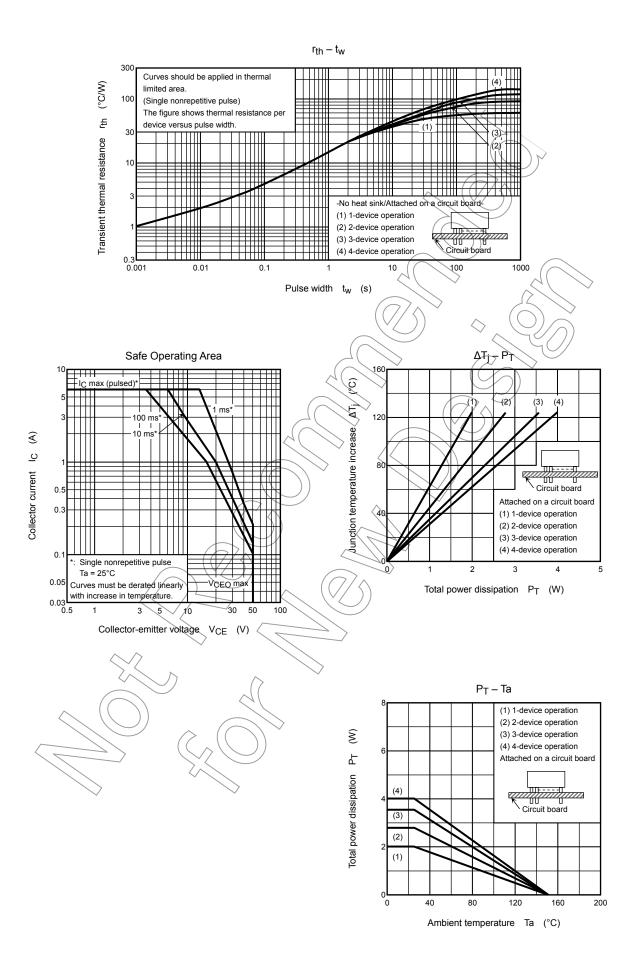
#### **Thermal Characteristics**

| Characteristics                                 | Symbol                 | Max  | Unit |  |
|---|------------------------|------|------|--|
| Thermal resistance from junction to ambient     | ΣR <sub>th (j-a)</sub> | 31.3 | °C/W |  |
| (4-device operation, Ta = 25°C)                 | . 0.7                  |      |      |  |
| Maximum lead temperature for soldering purposes | TL                     | 260  | °c ( |  |
| (3.2 mm from case for 10 s)                     | _                      |      |      |  |

## **Electrical Characteristics (Ta = 25°C)**

|   |                     |   |   | /_// |      | 1     | -    |  |
|---|---------------------|---|---|------|------|-------|------|--|
| Characteristics                                       |                     | Symbol                                      | Test Condition  | Min  | Тур. | Max   | Unit |  |
| Collector cut-off current                             |                     | I <sub>CBO</sub>                            | V <sub>CB</sub> = 45 V, I <sub>E</sub> = 0 A            | _    | _    | 10    | μΑ   |  |
| Collector cut-off cu                                  | rrent               | ICEO  | VCE = 45 V, I <sub>B</sub> = 0 A                        |      | _    | 10    | μΑ   |  |
| Emitter cut-off current                               |                     | IEBO  | V <sub>EB</sub> = 6 V, I <sub>C</sub> = 0 A             | 0.6  | _    | 20    | mA   |  |
| Collector-base breakdown voltage                      |                     | V <sub>(BR)</sub> CBO                       | 1e = 10 mA, I <sub>E</sub> = 0 A                        | 50   | 60   | 70    | V    |  |
| Collector-emitter breakdown voltage                   |                     | V (BR) CEO                                  | I <sub>C</sub> = 10 mA, I <sub>B</sub> = 0 A            | 50   | 60   | 70    | V    |  |
| DO comment main                                       |                     | hFE (1)                                     | V <sub>CE</sub> = 2 V, I <sub>C</sub> = 1 A             | 2000 | _    | 15000 | _    |  |
| DC current gain                                       | h <sub>FE</sub> (2) | V <sub>CE</sub> = 2 V, t <sub>C</sub> = 3 A | 1000  | _    | _    |       |      |  |
| Saturation voltage                                    | Collector-emitter   | VCE (sat)                                   | I <sub>C</sub> = 3 A, I <sub>B</sub> = 10 mA            |      | -    | 1.5   | V    |  |
|   | Base-emitter        | √V <sub>BE (sat)</sub>                      | IC = 3 A, 1 <sub>B</sub> = 10 mA                        | _    | _    | 2.0   |      |  |
| Transition frequency                                  |                     | fT  | $V_{CE} = 2 \text{ V, I}_{C} = 0.5 \text{ A}$           |      | 60   | _     | MHz  |  |
| Collector output capacitance                          |                     | C <sub>ob</sub>                             | V <sub>CB</sub> = 10 V, I <sub>E</sub> = 0 A, f = 1 MHz | _    | 30   | _     | pF   |  |
| Turn-on time  Switching time  Storage time  Fall time | ton                 | Output Input IB1                            |   | 0.2  | _    |       |      |  |
|   | Storage time        | tstg  | 20 μs   B2   W   S   C   S   C   C   S   C   C   C   C  |      | 3.0  | _     | μs   |  |
|   | Fall time           | \rightarrow tf                              | $I_{B1} = -I_{B2} = 10 \text{ mA, duty cycle} \le 1\%$  | _    | 0.5  |       |      |  |







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